

## ABSTRACT OF THE DISCLOSURE

The semiconductor device according to the present invention is equipped with a plurality of electronic circuits including at least one semiconductor integrated circuit chip, and a  
5 plurality of intermediate substrates interposed between the electronic components and a package and mounting the electronic components directly on its one major face, where each of the electronic component has on the one major face at least a plurality of first electrodes connected to the electronic components, a  
10 plurality of second electrodes for external connection, and internal connection electrodes for connecting between the electronic components including the connection between the first electrodes and the second electrodes that are mutually corresponding.